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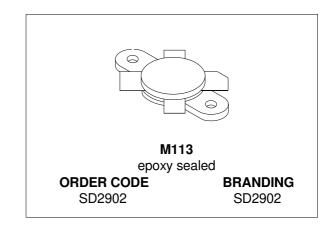
SD2902

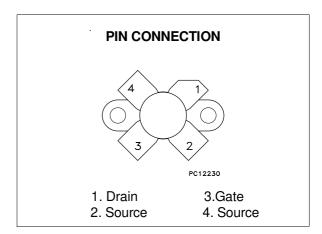
RF POWER TRANSISTORS HF/VHF/UHF N-CHANNEL MOSFETs

- GOLD METALLIZATION
- COMMON SOURCE CONFIGURATION
- 2 500 MHz
- 15 WATTS
- 28 VOLTS
- 12.5 dB MIN. AT 400 MHz
- CLASS A OR AB OPERATION
- EXCELLENT THERMAL STABILITY

DESCRIPTION

The SD2902 is a gold metallized N-Channel MOS field-effect RF power transistor. It is intended for use in 28 V DC large signal applications up to 500 MHz





ABSOLUTE MAXIMUM RATINGS (Tcase = 25 °C)

Symbol	Parameter	Value	Unit
$V_{(BR)DSS}$	Drain Source Voltage	65	V
V_{DGR}	Drain-Gate Voltage ($R_{GS} = 1M\Omega$)	65	V
V_{GS}	Gate-Source Voltage	±20	V
I_{D}	Drain Current	2.5	Α
P _{DISS}	Power Dissipation	58.3	W
Tj	Max. Operating Junction Temperature	200	°C
T _{STG}	Storage Temperature	-65 to 150	°C

THERMAL DATA

R _{th(j-c)}	Junction-Case Thermal Resistance	3.0	°C/W
$R_{th(c-s)}$	Case-Heatsink Thermal Resistance *	0.30	°C/W

^{*} Determined using a flat aluminum or copper heatsink with thermal compound applied (Dow Corning 340 or equivalent).

November 1999 1/8

ELECTRICAL SPECIFICATION $(T_{case} = 25 \degree C)$

STATIC

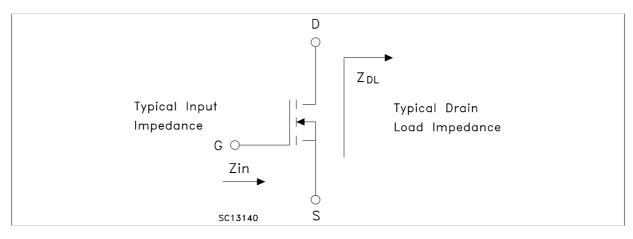
Symbol		Parameter		Min.	Тур.	Max.	Unit
$V_{(BR)DSS}$	$V_{GS} = 0V$	$I_{DS} = 15 \text{ mA}$		65			V
I _{DSS}	V _{GS} = 0V	V _{DS} = 28 V				1.5	mA
I _{GSS}	V _{GS} = 20V	V _{DS} = 0 V				1.0	μΑ
V _{GS(Q)}	$V_{DS} = 10V$	I _D = 30 mA		1.0		6.0	V
V _{DS(ON)}	V _{GS} = 10V	I _D = 1.5 A				1.6	V
g FS	$V_{DS} = 10V$	I _D = 1.5 A		0.6			mho
C _{ISS}	$V_{GS} = 0V$	V _{DS} = 28 V	f = 1 MHz		23		pF
Coss	$V_{GS} = 0V$	V _{DS} = 28 V	f = 1 MHz		18		pF
C _{RSS}	$V_{GS} = 0V$	V _{DS} = 28 V	f = 1 MHz		3.5		рF

REF. 1021308K

DYNAMIC

Symbol	Parameter				Min.	Тур.	Max.	Unit
P _{OUT}	f = 400 MHz	$V_{DD} = 28 \text{ V}$		$I_{DQ} = 25 \text{ mA}$	15			W
G _{PS}	f = 400 MHz	V _{DD} = 28 V	P _{out} = 15 W	$I_{DQ} = 25 \text{ mA}$	12.5	13.5		dB
η_D	f = 400 MHz	V _{DD} = 28 V	P _{out} = 15 W	$I_{DQ} = 25 \text{ mA}$	45	55		%
	f = 400 MHz All Angles	$V_{DD} = 28 \text{ V}$	$P_{out} = 15 W$	$I_{DQ} = 25 \text{ mA}$	10:1			VSWR

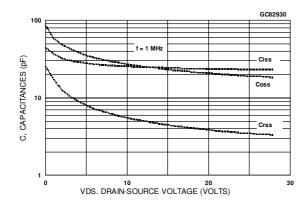
IMPEDANCE DATA



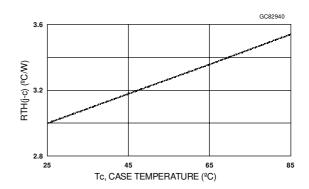
FREQ.	Z _{IN} (Ω)	Z _{DL} (Ω)
400 MHz	2.6 - j 6.5	7.8 + j 10

TYPICAL PERFORMANCE

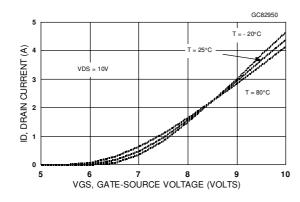
Capacitance vs Drain-Source Voltage



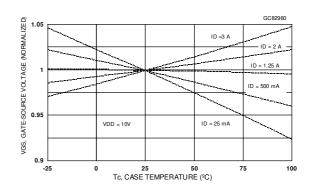
Maximum Thermal Resistance vs Case Temperature



Drain Current vs Gate Voltage

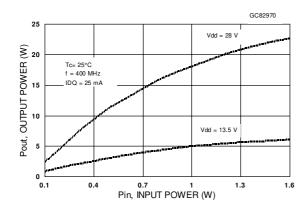


Gate-Source Voltages vs Case Temperature

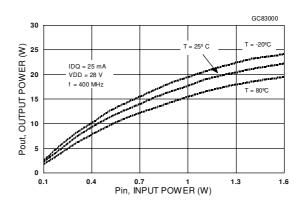


TYPICAL PERFORMANCE

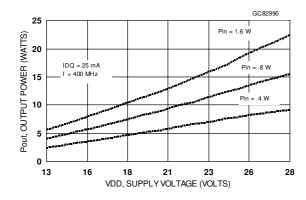
Output Power vs Input Power



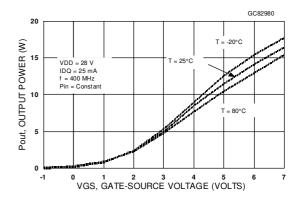
Output Power vs Input Power



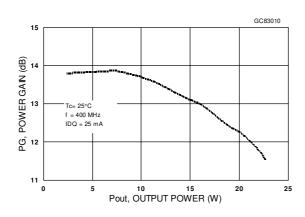
Output Power vs Voltage Supply



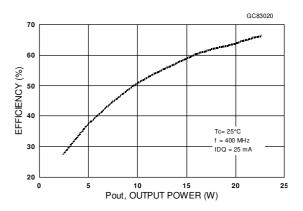
Output Power vs Gate Voltage



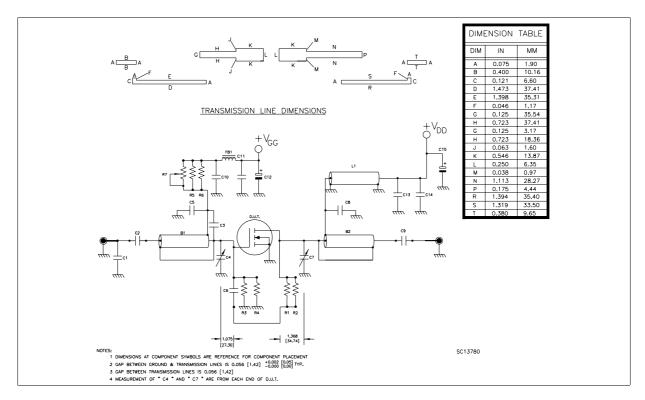
Power Gain vs Output Power



Efficiency vs Output Power



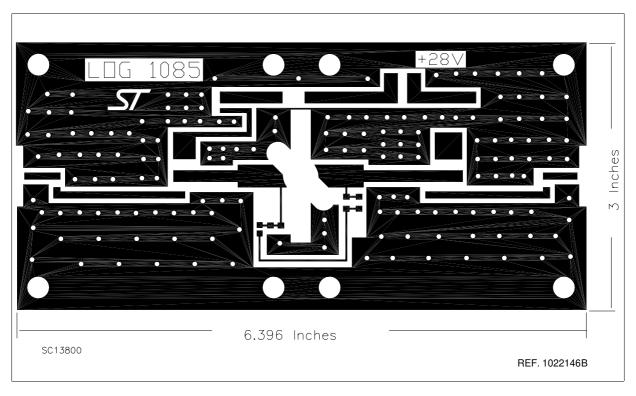
400 MHz Test Circuit Schematic



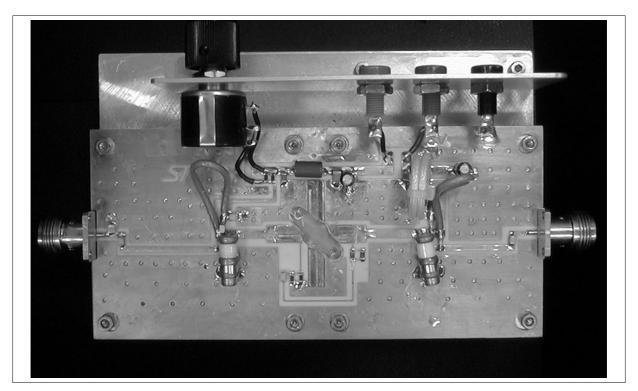
400 MHz Test Circuit Component Part List

COMPONENT	PART NO.	VENDOR	DESCRIPTION
			ε r=3.38, 10z ED Cu BOTH SIDES
PCB	N0320X1011HE	ROGERS CORP.	WOVEN GLASS REINFORCED CERAMIC HYDROCARBON 0.032" THK,
C1	ATC100B130JW500X	ATC	13pF ATC 100B SURFACE MOUNT CERAMIC CHIP CAPACITOR
C2	ATC100B370KW300X		270pF ATC 100B SURFACE MOUNT CERAMIC CHIP CAPACITOR
C3	ATC100B510KW500X		51pf atc 100b surface mount ceramic chip capacitor
C4	5601PC	JOHANSON	1-30pF STANDARD AIR DIELECTRIC VARIABLE CAPACITOR
C5	ATC100B121KW300X	-	120pF ATC 100B SURFACE MOUNT CERAMIC CHIP CAPACITOR
C6	ATC100B121KW300X		120pF STANDARD AIR DIELETRIC VARIABLE CAPACITOR 120pF ATC 100B SURFACE MOUNT CERAMIC CHIP CAPACITOR
<u>са</u> С7	ATC100B121KW300X 5601PC	JOHANSON	120pf atc 100B surface mount ceramic chip capacitor 1-30pf standard air dieletric variable capacitor
C8	ATC100B271KW200X	ATC	
C10 C9	ATC200B103KW50X		270pF ATC 100B SURFACE MOUNT CERAMIC CHIP CAPACITOR
<u> </u>	C1812X7R501 – 104KNE		0.1\(\mu F \) 500V SURFACE MOUNT CERAMIC CHIP CAPACITOR 10000\(\mu F \) ATC 200B SURFACE MOUNT CERAMIC CHIP CAPACITOR
012	SKR100M1JD11	MALLORY	10 \(\mu\)F \(/\) 63V ALUMINUM ELECTROLYTICS RADIAL LEAD CAPACITOR
213	ATC200B103KW50X		10000pF ATC 200B SURFACE MOUNT CERAMIC CHIP CAPACITOR
214	C1812X7R501-104KNE		0.1µF / 500V SURFACE MOUNT CERAMIC CHIP CAPACITOR
215	SKR100M1JD11	MALLORY	10μ F $/$ 63V ALUMINUM ELECTROLYTICS RADIAL LEAD CAPACITOR
			FLEXIBLE COAXIAL CABLE OR EQUIVALENT
B1	RG316-25		BALUN, RG316-25, 25 OHM, NOM O.D. 0.090[2.29], L=3.00[76.19]
			FLEXIBLE COAXIAL CABLE OR EQUIVALENT
B2	RG316-25		BALUN, RG316-25, 25 OHM, NOM O.D. 0.090[2.29], L=3.00[76.19]
			FLEXIBLE COAXIAL CABLE OR EQUIVALENT
L1	RG316		INDUCTOR, RG316, 50 OHMS, NOM O.D. 0.090[2.29], L=5.5"[139.70] LG
FB1	2943666671	FAIR-RITE CORP	EMI SHIELD BEAD, 2 1/2 TURN WOUND WITH TINNED Cu WIRE #24 AWO
R1	CR1206-4W-821JT		820 OHM 1/4 W SURFACE MOUNT CHIP RESISTOR
R2	CR1206-4W-821JT		820 OHM 1/4 W SURFACE MOUNT CHIP RESISTOR
R3	CR1206-4W-471JT		470 OHM 1/4 W SURFACE MOUNT CHIP RESISTOR
R4	CR1206-4W-471JT		470 OHM 1/4 W SURFACE MOUNT CHIP RESISTOR
R5	CR1206-4W-471JT		470 OHM 1/4 W SURFACE MOUNT CHIP RESISTOR
R6	CR1206-4W-471JT	VENKEI	470 OHM 1/4 W SURFACE MOUNT CHIP RESISTOR

400 MHz Test Circuit Photomaster

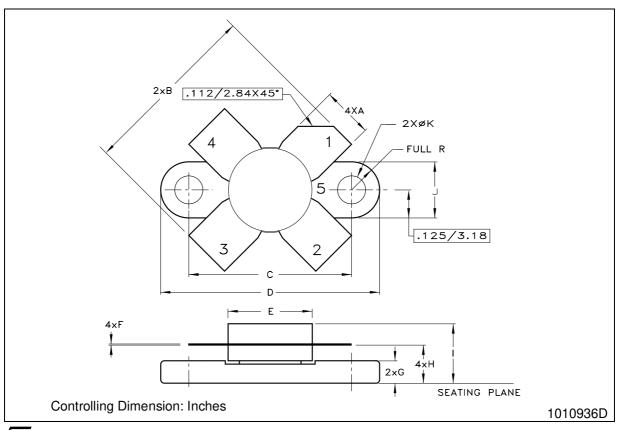


Production Test Fixture



M113 (.380 DIA 4/L N/HERM W/FLG) MECHANICAL DATA

DIM.	mm			inch			
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
Α	5.59		5.84	0.220		0.230	
В	19.81		20.83	0.780		0.820	
С	18.29		18.54	0.720		0.730	
D	24.64		24.89	0.970		0.980	
Е	9.40		9.78	0.370		0.385	
F	0.10		0.15	0.004		0.006	
G	2.16		2.67	0.085		0.105	
Н	4.06		4.57	0.160		0.180	
ı			7.14			0.281	
J	6.22		6.48	0.245		0.255	
K	3.05		3.30	0.120		0.130	



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